-	Application No.		Applicant(s)	
Notice of Allowability	09/960,089		KOOPMANS, MICHEL	
	Examiner			
	Alonzo Cha	mbliss	2827	
The MAILING DATE of this communication at All claims being allowable, PROSECUTION ON THE MERITS herewith (or previously mailed), a Notice of Allowance (PTOL NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATEN of the Office or upon petition by the applicant. See 37 CFR 1	S IS (OR REMAIN: 85) or other appro IT RIGHTS . This a	S) CLOSED in this opriate communicat application is subject	application. If not includition will be mailed in due	ded course. THIS
 This communication is responsive to <u>amendment B file</u> The allowed claim(s) is/are <u>1-35, 76-86, and 98-108</u>. The drawings filed on are accepted by the Exale Acknowledgment is made of a claim for foreign priority a) All b) Some* c) None of the: 	miner.	§ 119(a)-(d) or (f).		
1. Certified copies of the priority documents	have been receive	d.		
2. Certified copies of the priority documents	have been receive	d in Application No	· ·	
Copies of the certified copies of the priorit International Bureau (PCT Rule 17.2(a) * Certified copies not received: Acknowledgment is made of a claim for domestic prior)).		•	ation from the
(a) The translation of the foreign language provision	nal application has	been received.		
6. Acknowledgment is made of a claim for domestic prior	ity under 35 U.S.C	. §§ 120 and/or 121	1.	
Applicant has THREE MONTHS FROM THE "MAILING DATI below. Failure to timely comply will result in ABANDONMEN" 7. A SUBSTITUTE OATH OR DECLARATION must be supported by the support of the	T of this application submitted. Note the	n. THIS THREE-N e attached EXAMIN	IONTH PERIOD IS NOT IER'S AMENDMENT or	T EXTENDABLE
 8. CORRECTED DRAWINGS must be submitted. (a) including changes required by the Notice of Draft: 1) hereto or 2) to Paper No (b) including changes required by the proposed draw (c) including changes required by the attached Exam 	ving correction filed	d <u>21 April 2003,</u> wh	nich has been approved	•
Identifying indicia such as the application number (see 37 C each sheet.	FR 1.84(c)) should	be written on the dra	awings in the front (not th	e back) of
9. DEPOSIT OF and/or INFORMATION about the datached Examiner's comment regarding REQUIREMENT FO	leposit of BIOLO DR THE DEPOSIT	GICAL MATERIA OF BIOLOGICAL I	L must be submitted. MATERIAL.	Note the
Attachment(s)				
 1 Notice of References Cited (PTO-892) 3 Notice of Draftperson's Patent Drawing Review (PTO-94 5 Information Disclosure Statements (PTO-1449), Paper N 7 Examiner's Comment Regarding Requirement for Depos of Biological Material 	lo	4☐ Interview Sun 6☐ Examiner's A	rmal Patent Application nmary (PTO-413), Pape mendment/Comment tatement of Reasons for	r No

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DETAILED ACTION

 Amendment B filed on 4/21/03 has been fully considered and made of record in Paper No. 7.

Allowable Subject Matter

2. The following is a statement of reasons for the indication of allowance subject matter: the prior art of record does not teach or suggest the combination of a first semiconductor die with a plurality of bond pads and at least one redistribution bond pad circuit thereon, wherein the plurality of bond pads are electrically connected to integrated circuitry of the first semiconductor die and the redistribution bond pad circuit is electrically isolated from the integrated circuitry. A second semiconductor die having a plurality of bond pads, wherein active surface of the second die faces the active surface of the first die. An electrical connector extending between at least one of the plurality of bond pads on the second die and at least one redistribution bond pad of the plurality of redistribution bond pads on the first die in claims 1 and 22.

A first semiconductor die with a plurality of bond pads and a second semiconductor die with a plurality of bond pads, wherein the active surface of the second die faces the active surface of the first die. The second die having a peripheral edge extending laterally beyond at least one corresponding peripheral edge of the plurality of peripheral edges of the first die. A third semiconductor die disposed directly below the second die, wherein the third die has a plurality of bond pads and at least one redistribution bond pad circuit thereon. The plurality of bond pads are electrically

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connected to integrated circuitry of the third semiconductor die and the redistribution bond pad circuit is independent from the integrated circuitry. An electrical connector extending between at least one of the plurality of bond pads on the second die to contact an area of a substrate adjacent to the peripheral edge of the first die in claim 98.

Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonzo Chambliss whose telephone number is (703) 306-9143. The fax phone number for the Group is (703) 308-772 or 7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the group receptionist whose telephone number is (703) 308-7956.

AC/June 29, 2003

Alonzo Chambliss Patent Examiner Art Unit 2827